

HANDLING PRECAUTIONS

Mechanical and heat stress sometimes damage dielectric ceramics of the capacitor. Be careful not to give the feed through ceramic capacitor the strong mechanical shock and the heat shock.

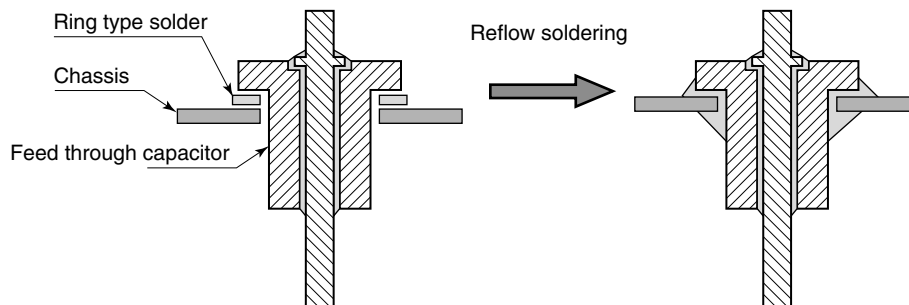
■ Soldering

1. Please use reflow soldering.

- Recommended Solder
Solder should be a ring type of which melting temperature is 185°C max.
- Recommended Method
Avoid rapid heating/cooling, preheat to around 130°C, and then process at 250°C max. in the reflow zone for 10 sec. max.

2. Recommended the hole size of chassis

Type	Hole size
PLE123	1.6±0.05
PLE12, 22, 32	2.1±0.05
PLE255	2.6±0.05
PLE23, 33	3.2±0.05



■ Soldering to Lead Wire

1. The following conditions are recommended for soldering to the lead wire.

- Recommended Method
Please use a soldering iron with as large heat capacity as possible.
Temperature of soldering iron should be 300°C max., applied for a maximum of 10 seconds.
Do not let the solder get within 3mm of the body of the part.

2. Don't bend a lead wire. Be careful that mechanical stress is not applied to the EMI filter itself when you unavoidably bend a lead wire.

■ Minimum packaging quantity

1. No pin type

2. With pin type
500 pcs/bag (All size)

Type	Quantity (pcs/bag)	Maximum quantity(pcs/bag)
PLE123	1,000	5,000
PLE12, 22, 32, 255, 23	1,000	15,000
PLE33	1,000	10,000